

**REMARKS**

Claims 1-11 are pending in the above-identified application. Claim 1 is amended. No claims are either added or canceled. It is respectfully submitted that this Amendment is fully responsive to the Office Action dated June 9, 2005.

The Drawings were objected to because Figures 1-3 were not designated as "Prior Art". Applicants have amended the drawings. Accordingly, Applicants respectfully request that the Examiner withdraw this objection.

Claims 1-8 were rejected under 35 U.S.C. 102(b) as being unpatentable over *Glenn* (U.S. Patent No. 5,949,655). Applicants amend claim 1. Support for this amendment is found, for example, on pages 9 and 10 of the specification. In view of this amendment and the following remarks, Applicants respectfully request that the rejection be withdrawn.

It is an object of the present invention to provide a semiconductor device for fingerprint recognition with high reliability that substantially obviates one or more of the problems caused by the limitations and disadvantages of the related art such as leakage of the resin or damaging of the chip or sensor unit at the time of production of the semiconductor device.

Particularly, the present invention provides a semiconductor device wherein the surface of the substrate on which the semiconductor chip is mounted is formed with plural terminals for external interconnection, with such a relationship that the height of the external interconnection terminal is larger than the height of the semiconductor chip as measured from the surface of the substrate as set forth in FIG. 4 and page 9, line 22-page 10, line 4. With such a construction, for example, it is possible to mount the semiconductor device on a mounting substrate of an

electronic apparatus easily by a flip-chip process in the state of exposing the fingerprint sensing surface of the semiconductor device at the opening of the substrate.

The semiconductor device of *Glenn* is not ready for mounting on an electronic apparatus or the like such as a fingerprint recognition apparatus by simple flip-chip process. *Glenn* fails to teach or even suggest either an external interconnection terminal as recited in claim 1 or a possible location of the substrate surface for providing such interconnection terminals. Also, *Glenn* is silent about the relationship in the height between the solder ball and the semiconductor chip. Therefore, each and every element of claim 1 is *not* found, either expressly or inherently, in *Glenn*. Accordingly, Applicants respectfully request that the rejection be withdrawn.

Claims 2-8 depend from claim 1. In view of the above remarks, Applicants respectfully request that the §102(b) rejections of these claims be withdrawn.

In view of the aforementioned amendments and accompanying remarks, Applicants respectfully submit that that the claims, as herein amended, are in condition for allowance. Applicants request such action at an early date.

If the Examiner believes that this application is not now in condition for allowance, the Examiner is requested to contact Applicants' undersigned attorney to arrange for an interview to expedite the disposition of this case.

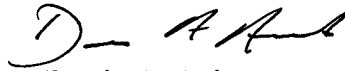
Application No. 10/765,999  
Attorney Docket No. 042063

Amendment under 37 C.F.R. §1.111

If this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,

**WESTERMAN, HATTORI, DANIELS & ADRIAN, LLP**

A handwritten signature in black ink, appearing to read "Darrin A. Auito".

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**AMENDMENTS TO THE DRAWINGS**

The attached Replacement Sheets of drawings include changes to Figs. 1-3. Each of these figures has been amended to include – Prior Art – in the legend.